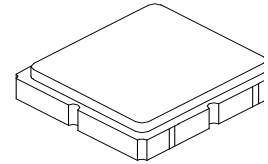


- No Matching Network Required for 50 Ω Operation
- Surface-mount 3.0 x 3.0 mm Package
- Complies with Directive 2002/95/EC (RoHS)



SF2211E

**1200 MHz
SAW Filter**



SM3030-6

Absolute Maximum Ratings

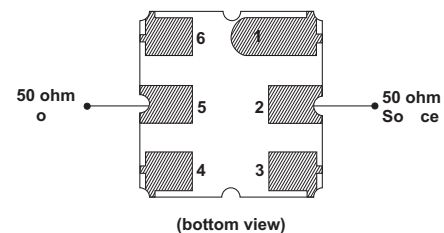
Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-55 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Component Storage Temperature Range	-55 to +95	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			1200		MHz
Insertion Loss, 1180 to 1220 MHz	IL			2.8	4.0	dB
Attenuation, 0 dB Reference:						dB
1080 MHz			35	60		
1100 MHz			45	60		
1300 MHz			40	48		
1320 MHz			35	52		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	945, YWWS					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

Electrical Connections

Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

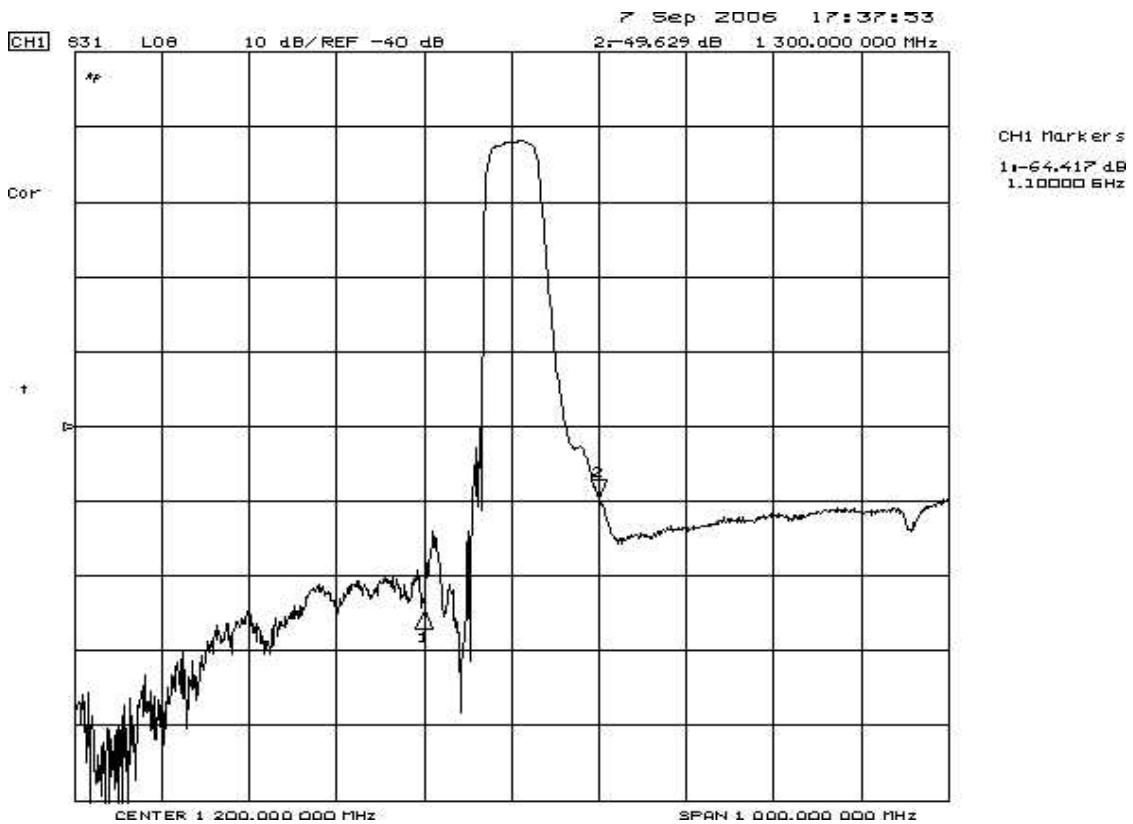
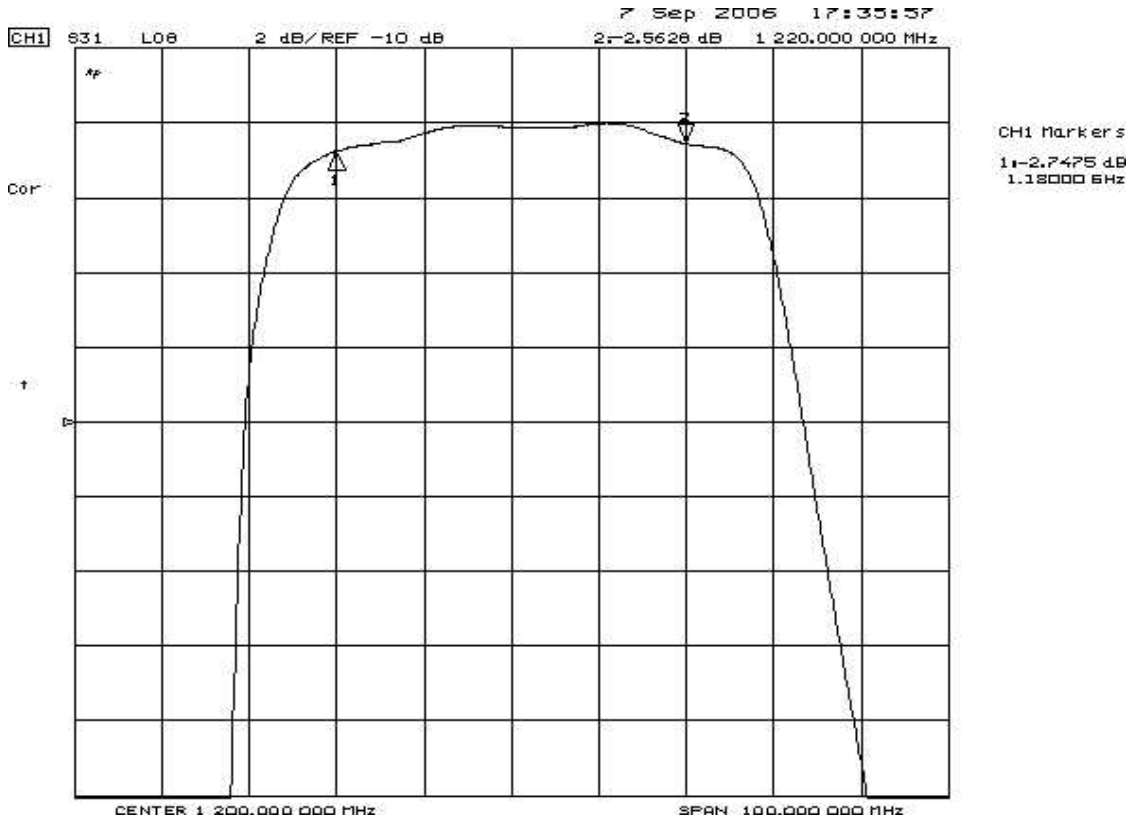


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

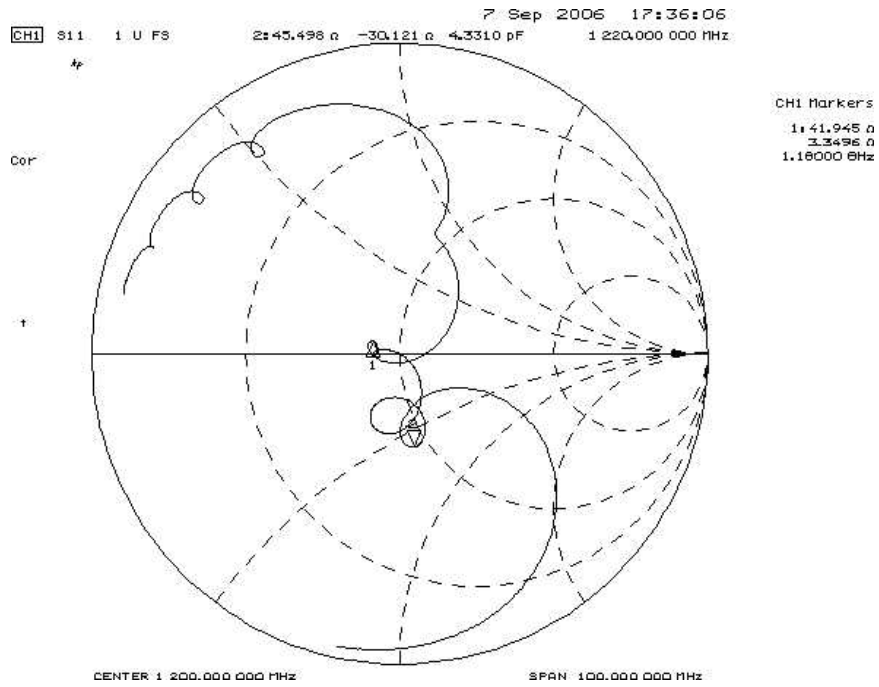
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

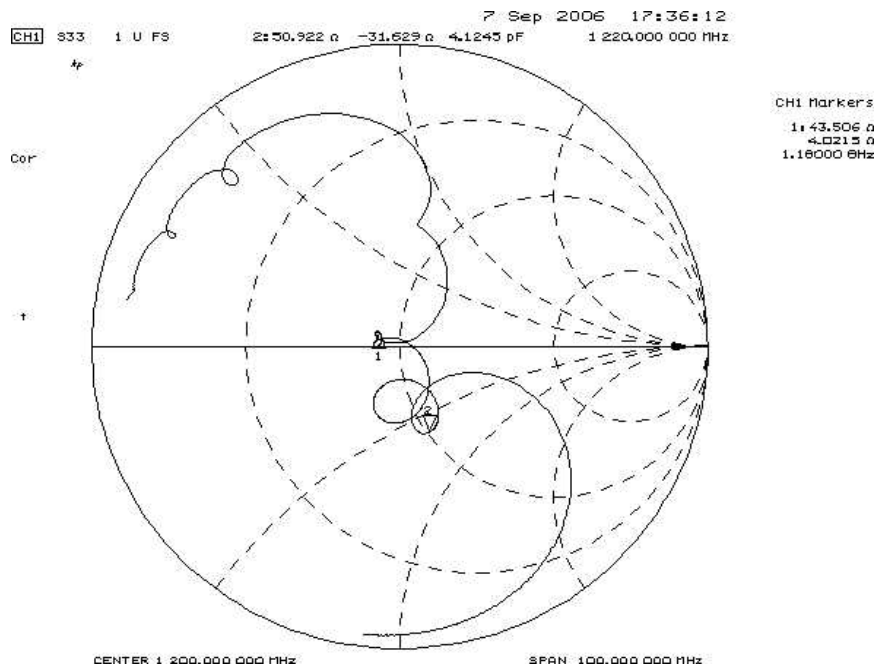
Filter Frequency Response



Filter Input Impedance



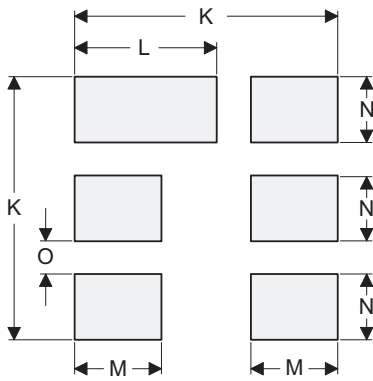
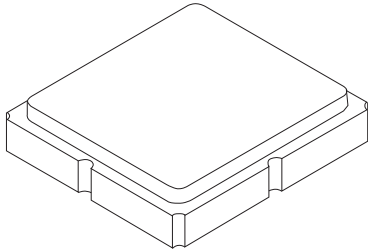
Filter Output Impedance



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case

3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

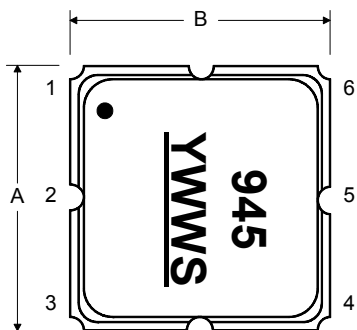
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic
Pb Free	

Top View



Bottom View

